



--9. A deposited-film formation apparatus comprising:

- A
- chamber;
- (a) a power-applying electrode and a flexible substrate in a vacuum
- (b) a discharge space between the power-applying electrode and the
- flexible substrate;
- (c) a material gas feed into the vacuum chamber;
- wherein the substrate can serve as an electrode disposed opposing the power-applying electrode and wherein the power-applying electrode has an undulation on its surface on the side of the discharge space such that the distance between the substrate and the power-applying electrode is a predetermined value in accordance with the curvature of the substrate.--
- 5-317

REMARKS

The Examiner required restriction between Group I, claims 1-6, drawn to an apparatus and Group II, claims 7 and 8, drawn to a method. Applicants provisionally wish to elect with traverse, Group I, claims 1-6 and request rejoinder of Group II, claims 7 and 8 upon allowance of the apparatus claims.

In addition, Applicants have provided an additional apparatus claim in order to encompass an additional embodiment.

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